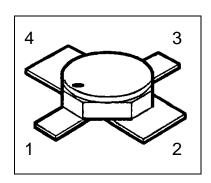


BFY182(ES)

Features

- For low noise, high-gain broadband amplifiers at collector currents from 1 mA to 20 mA
- Hermetically sealed microwave package
- f_T= 8GHz
 F = 2.4 dB at 2 GHz



Product validation

• **@esa** Space Qualified

ESCC Detail Spec. No.: 5611/006 Type Variant No. 04

Description

ESD: Electrostatic discharge sensitive device, observe handling precautions!

Table 1 Product information

Туре	Comment	Pin Config	Package			
		1	2	3	4	
BFY182(ES)	For flight use	_	_	Б	_	Miana V1
BFY182(P) ¹	Not for flight use ¹		E	В	E	Micro-X1

¹ (P) parts have the same fit, form and function as (ES) parts, no screening acc. to Chart F3 in ESCC Generic Specification No. 5010

BFY182(ES)

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BFY182(ES)

Maximum ratings



Maximum ratings 1

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.	1		
Collector-emitter voltage	$V_{\sf CEO}$	-	-	12	V		
Collector-emitter voltage	V_{CES}	-	-	20	V	V _{BE} =0	
Collector-base voltage	V_{CBO}	-	-	20	V		
Emitter-base voltage	V_{EBO}	-	-	2	V		
Collector current	I _C	-	-	35	mA		
Base current ¹	I _B	-	-	4	mA		
Total power dissipation ²	P _{tot}	-	-	250	mW	<i>T</i> _S ≤ 136 °C	
Junction temperature	T _j	-	-	200	°C		
Operating temperature	Top	-65	-	200	°C		
Storage temperature	\mathcal{T}_{stg}	-65	-	200	°C		

 $^{^{1}}$ The maximum permissible base current for V_{FBE} measurements is 20mA (spot-measurement duration < 1s)

 $^{^{2}}$ For $T_{S} > 136$ °C derating is required. T_{S} is measured on the collector lead at the soldering point to the PCB

BFY182(ES)

Thermal characteristics



2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Thermal resistance, junction –soldering point	$R_{th,JS}$	-	-	255	K/W	T _S is measured on the collector lead at the soldering point to the PCB	
Soldering Temperature	$T_{ m sol}$	-	-	250	°C	Duration 5 seconds maximum at a distance of not less than 0.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.	

BFY182(ES)

Electrical characteristics



3 Electrical characteristics

at T_A=25°C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Collector-base cutoff current	I _{CBO}	-	-	100	μΑ	$V_{\rm CB} = 20 \text{V}, I_{\rm E} = 0 \text{A}$
Collector-emitter cutoff current ¹	I _{CEX}	-	-	200	μΑ	$V_{CE} = 12V, I_B = 0.2 \mu A$
Collector-base cutoff current	I _{CBO}	-	-	50	nA	$V_{CB} = 10V, I_E = 0A$
Emitter base cuttoff current	I _{EBO}	-	-	25	μΑ	$V_{\rm EB} = 2V, I_{\rm C} = 0A$
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μΑ	$V_{\rm EB} = 1 \text{V}, I_{\rm C} = 0 \text{A}$
Base-Emitter forward voltage	V_{FBE}	-	-	1	٧	$I_{\rm E}$ = 20mA, $I_{\rm C}$ = 0A
DC current gain	$h_{ extsf{FE}}$	55	100	170	-	$I_{\rm C} = 5 {\rm mA}, V_{\rm CE} = 6 {\rm V}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Transition frequency	f_{T}	6.5	7.5 8	-	GHz	I_{C} = 15mA, V_{CE} = 5V, f = 500MHz I_{C} = 15mA, V_{CE} = 8V, f = 500MHz	
Collector-base capacitance	ССВ	-	0.26	0.36	pF	V _{CB} = 10V, V _{BE} = vbe= 0, f= 1MHz	
Collector-emitter capacitance	C _{CE}	-	0.34	-	pF	V _{CE} = 10V, V _{BE} = vbe= 0, f= 1MHz	
Emitter-base capacitance	C _{EB}	-	0.8	1.1	pF	V _{EB} =0.5V, V _{CB} = vcb= 0, f= 1MHz	
Noise Figure	F	-	2.4	2.9	dB	I_C = 5mA, V_{CE} = 5V, f = 2GHz, Z_S = Z_{Sopt}	
Power Gain ²	G_{ma}	13.5	14.5	-	dB	I_C = 15mA, V_{CE} = 5V, f = 2GHz, Z_S = Z_{Sopt} , Z_L = Z_{Lopt}	
Transducer gain	S _{21e} ²	10	11	-	dB	I_{C} = 15mA, V_{CE} = 5V, f = 2GHz, Z_{S} = Z_{L} = 50 Ω	

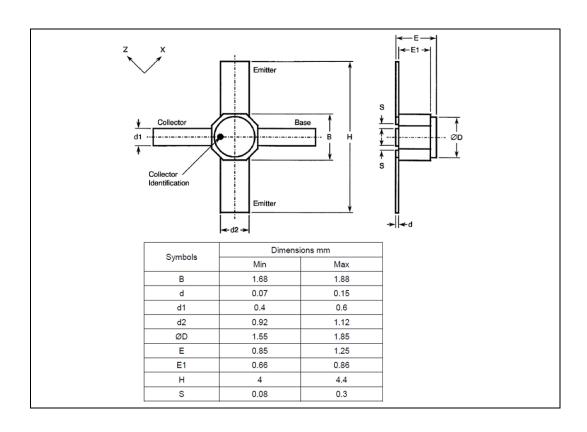
¹ This test assures $V_{(BR)CE0} > 12V$

 $^{^{2}}G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^{2} - 1}), G_{ms} = \left| \frac{S21}{S12} \right|$

Package outlines



4 Package outlines



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